IN THE CLAIMS:

Please amend the claims as follows:

1. (Twice Amended) A method of forming a probe card comprising:

providing a substrate having a first surface and a second surface;

disposing a plurality of conductive traces adjacent at least one of the first surface and the second surface;

providing a plurality of probe elements in electrical communication with the plurality of conductive traces; and

providing a plurality of fuse elements in respective electrical communication with at least some of the plurality of conductive traces, at least some of the plurality of fuse elements disposed immediately adjacent the at least one of the first surface and the second surface, at least some of said plurality of fuse elements comprising at least two types of fuses of an active fuse element, a passive fuse element, a self-resetting fuse element, a repairable fuse element, and a replaceable fuse element.

2. (Original) The method of claim 1, wherein said providing a plurality of fuse elements comprises providing a fuse element of the plurality of fuse elements in respective electrical communication with substantially each of the plurality of conductive traces.

3. (Previously Amended) The method of claim 1, wherein said providing a plurality of fuse elements comprises providing at least one fuse element of the plurality of fuse elements configured to be replaceable or repairable after being tripped.

4. (Previously Amended) The method of claim 3, wherein the at least one fuse element of the plurality of fuse elements is formed of a material selected from the group consisting of titanium tungsten, aluminum, platinum silicide, copper, nichrome, doped polysilicon, metal silicide, and alloys of any thereof.

5. (Previously Amended) The method of claim 3, wherein said providing a plurality of fuse elements comprises forming at least some of the plurality of fuse elements using a deposition process.

Claims 6-55. (Withdrawn)